

**HEXFRED  
ULTRAFast, SOFT RECOVERY DIODE**

$V_R = 600V$
$V_F = 1.75V$
$Q_{rr} = 380nC$
$di_{(rec)M}/dt = 400A/\mu s$

**Features**

- Reduced RFI and EMI
- Reduced Snubbing
- Extensive Characterization of Recovery Parameters
- Hermetically Sealed
- Ceramic Eyelets

**Description**


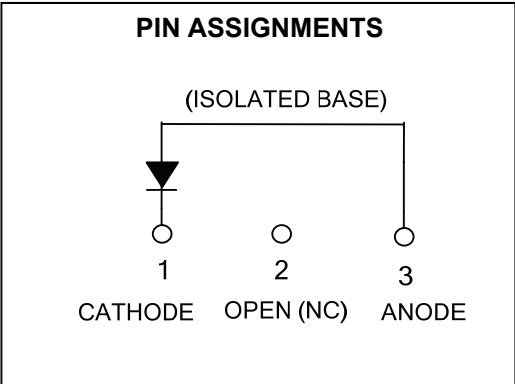
HFA35HB60 is part of the International Rectifier HiRel family of products. These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and di/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

**Absolute Maximum Ratings**

Characteristics	Characteristics	Max.	Units
$V_R$	D.C. Reverse Voltage	600	V
$I_F @ T_C = 100^\circ C$	Continuous Forward Current ①	22	A
$I_{FSM} @ T_C = 25^\circ C$	Single Pulse Forward Current ②	225	A
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	83	W
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ C$

**Notes:**

- ① D.C. = 50% rectangle wave
- ② 1/2 sine wave, 60Hz, Pulse Width = 8.33ms

<p><b>CASE STYLE</b></p>  <p><b>TO-254AA</b></p>	<p><b>PIN ASSIGNMENTS</b></p> 
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**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

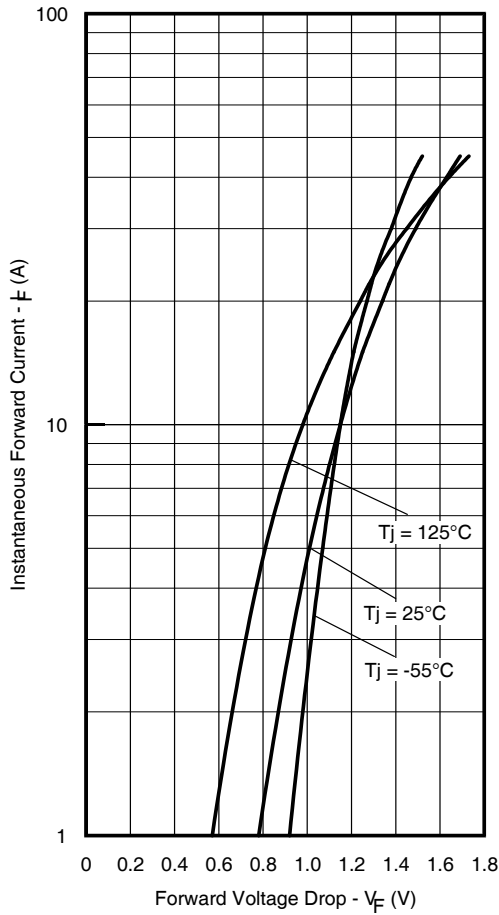
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{BR}$	Cathode Anode Breakdown Voltage	600	—	—	V	$I_R = 100\mu\text{A}$
$V_{FM}$	Max. Forward Voltage See Fig. 1	—	—	1.55	V	$I_F = 22\text{A}, T_J = -55^\circ\text{C}$
		—	—	1.75		$I_F = 22\text{A}, T_J = 25^\circ\text{C}$
		—	—	2.25		$I_F = 45\text{A}, T_J = 25^\circ\text{C}$
		—	—	1.64		$I_F = 22\text{A}, T_J = 125^\circ\text{C}$
$I_{RM}$	Max. Reverse Leakage Current See Fig. 2	—	—	10	$\mu\text{A}$	$V_R = V_R \text{ Rated}$
		—	—	1.0	$\text{mA}$	$V_R = 480\text{V } T_J = 125^\circ\text{C}$
$C_T$	Junction Capacitance, See Fig. 3	—	56	59	$\text{pF}$	$V_R = 200\text{V}$
$L_S$	Series Inductance	—	8.7	—	$\text{nH}$	Measured from center of bond pad to end of anode bonding wire

**Dynamic Recovery Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

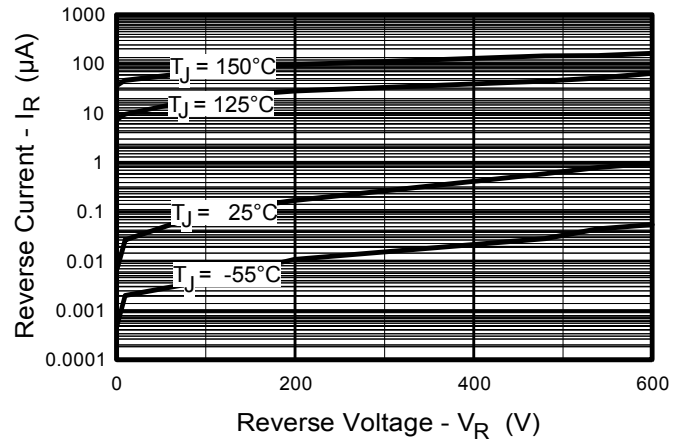
	Parameter	Min.	Typ.	Max.	Units	Test Conditions	
$t_{rr1}$	Reverse Recovery Time	—	60	97	ns	$T_J = 25^\circ\text{C}$	$I_F = 22\text{A}$  $V_R = 200\text{V}$  $di_f/dt = 200\text{A}/\mu\text{s}$
$t_{rr2}$	See Fig. 5	—	110	165		$T_J = 125^\circ\text{C}$	
$I_{RRM1}$	Peak Recovery Current	—	5.2	11	A	$T_J = 25^\circ\text{C}$	
$I_{RRM2}$	See Fig. 6	—	8.5	13		$T_J = 125^\circ\text{C}$	
$Q_{rr1}$	Reverse Recovery Charge	—	190	380	nC	$T_J = 25^\circ\text{C}$	
$Q_{rr2}$	See Fig. 7	—	560	840		$T_J = 125^\circ\text{C}$	
$di_{(rec)M}/dt1$	Peak Rate of Fall of Recovery Current	—	270	400	$\text{A}/\mu\text{s}$	$T_J = 25^\circ\text{C}$	
$di_{(rec)M}/dt1$	During $t_b$ - See Fig. 8	—	170	250		$T_J = 125^\circ\text{C}$	

**Thermal - Mechanical Characteristics**

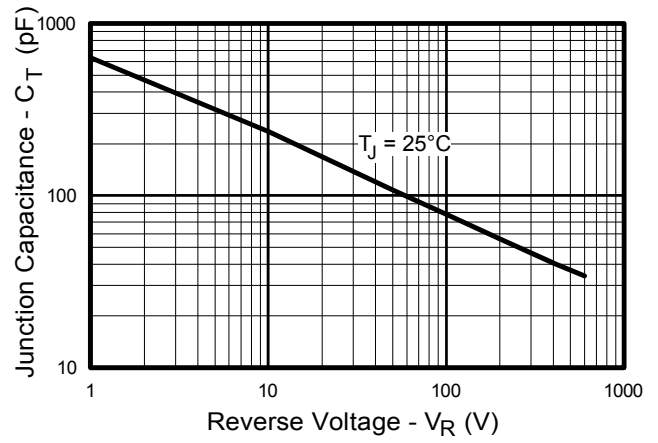
	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case, Single Leg Conducting	—	1.5	$^\circ\text{C}/\text{W}$
Wt	Weight	9.3	—	g



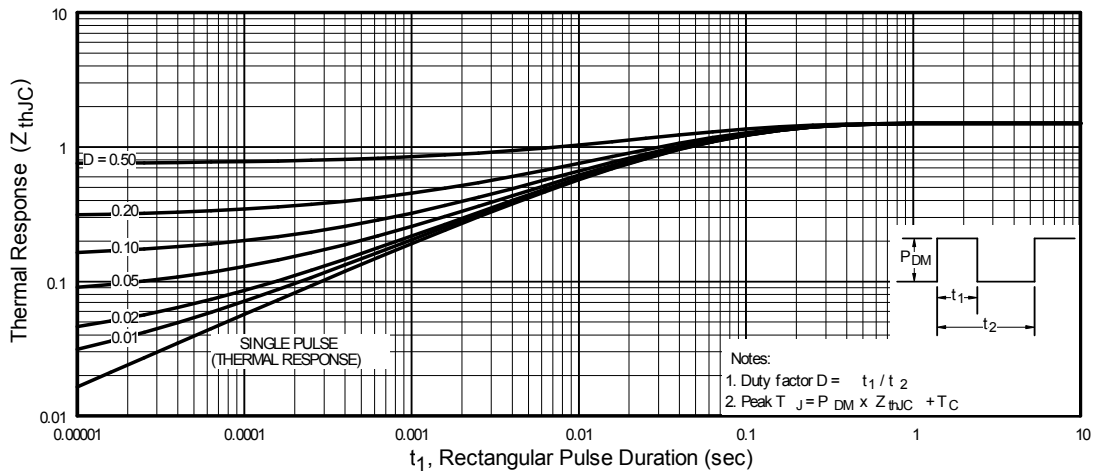
**Fig. 1** Typical Forward Voltage Drop Vs. Instantaneous Forward Current



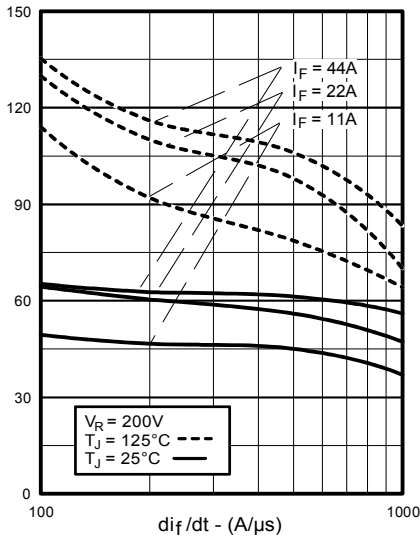
**Fig. 2** Typical Values of Reverse Current Vs. Reverse Voltage



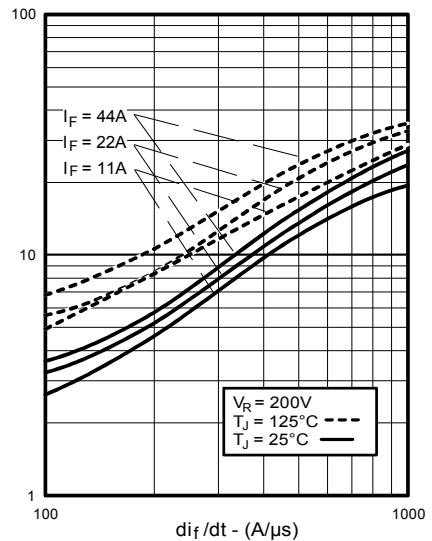
**Fig. 3** Typical Junction Capacitance Vs. Reverse Voltage



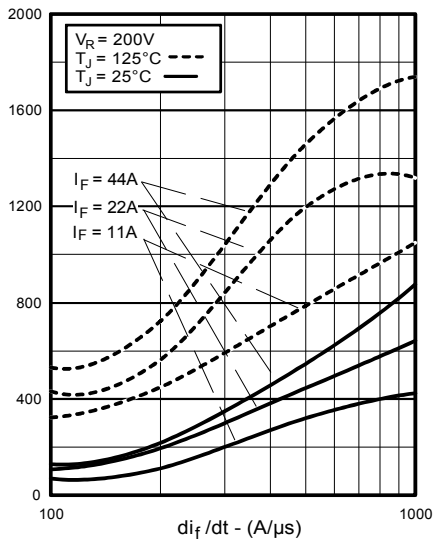
**Fig. 4** Maximum Thermal Impedance  $Z_{thJC}$  Characteristics



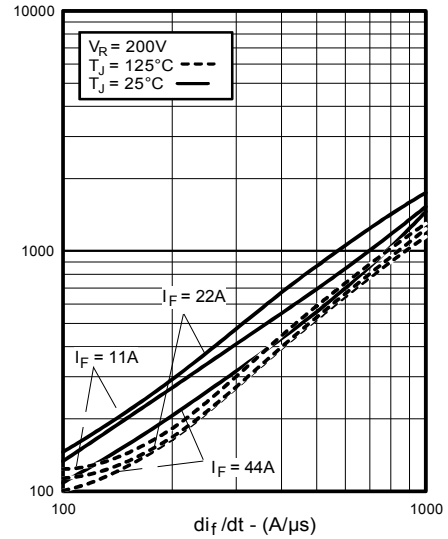
**Fig. 5** Typical Reverse Recovery Vs  $di_f/dt$



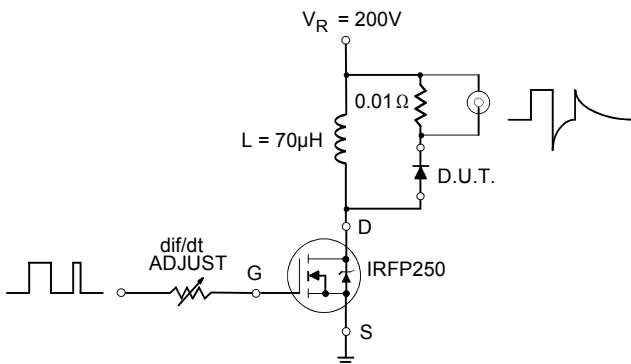
**Fig. 6** Typical Recovery Current Vs  $di_f/dt$



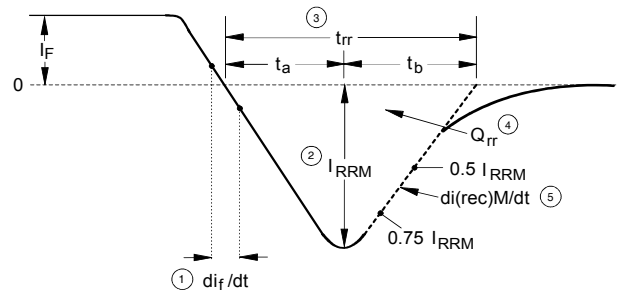
**Fig. 7** Typical Stored Charge Vs  $di_f/dt$



**Fig. 8** Typical  $di_{(rec)M}/dt$  Vs  $di_f/dt$



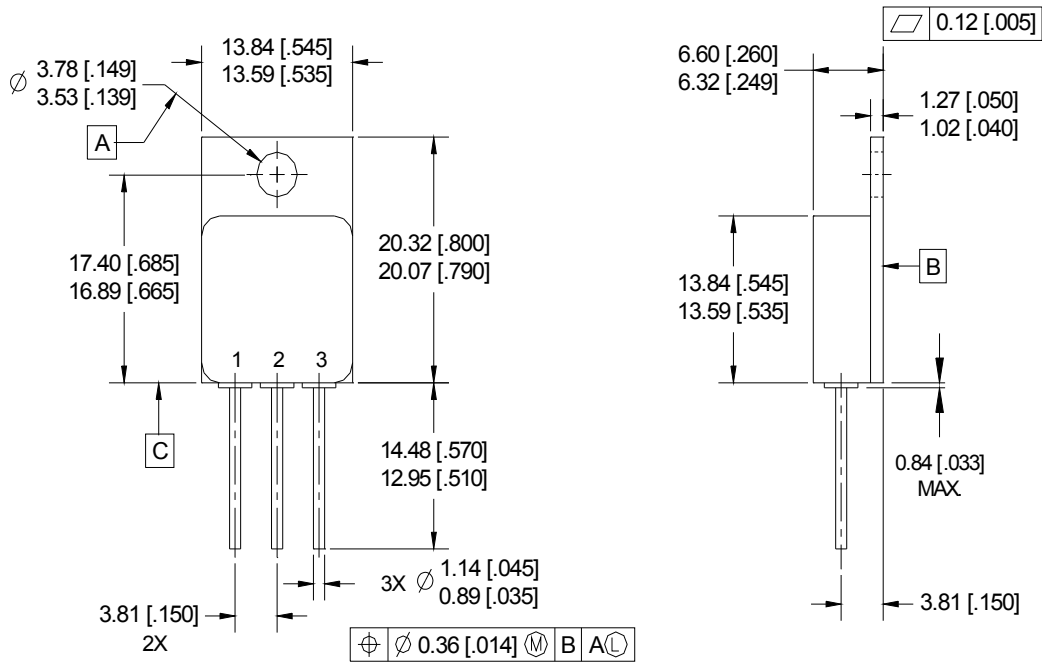
**Fig. 9** Typical Reverse Recovery Parameter Test Circuit



- ①  $di_f/dt$  - Rate of change of current through zero crossing.
- ②  $I_{RRM}$  - Peak reverse recovery current.
- ③  $t_{rr}$  - Reverse recovery time measured from zero crossing to point where a line passing through  $0.75I_{RRM}$  and  $0.5I_{RRM}$  extrapolated to zero current.
- ④  $Q_{rr}$  - Area under curve defined by  $t_{rr}$  and  $I_{RRM}$  -  $Q_{rr} = (t_{rr} \times I_{RRM}) / 2$
- ⑤  $di_{(rec)M}/dt$  - Peak rate of change of current during  $t_b$  position of  $t_{rr}$ .

**Fig. 10** Reverse Recovery Waveform and Definitions

**Case Outline and Dimensions — TO-254AA**



**NOTES:**

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE TO-254AA.

**PIN ASSIGNMENTS**

Refer to page 1.

**BERYLLIA WARNING PER MIL-PRF-19500**

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.

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